ALPHA & OMEGA SEMICONDUCTOR

AO4712

30V N-Channel MOSFET

SRFET™

General Description

SRFET™ AO4712 uses advanced trench technology with a monolithically integrated Schottky diode to provide excellent $R_{DS(ON)}$,and low gate charge. This device is suitable for use as a low side FET in SMPS, load switching and general purpose applications.

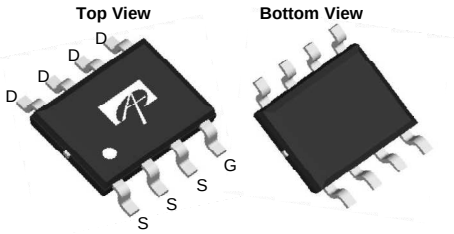
Product Summary

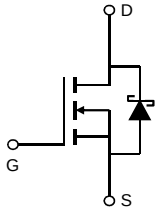
V_{DS}	30V
I_D (at V_{GS}=10V)	13A
$R_{DS(ON)}$ (at V_{GS}=10V)	< 11mΩ
$R_{DS(ON)}$ (at V_{GS} = 4.5V)	< 14mΩ

100% UIS Tested
100% R_g Tested

Green Product

SOIC-8





SRFET™
Soft **R**ecovery MOS**FET**:
Integrated Schottky Diode

Absolute Maximum Ratings T_A=25℃ unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±12	V
Continuous Drain Current	T_A=25℃	I_D	13	A
	T_A=70℃		10	
Pulsed Drain Current [C]		I_{DM}	68	
Avalanche Current [C]		I_{AS}, I_{AR}	15	A
Avalanche energy L=0.1mH [C]		E_{AS}, E_{AR}	11	mJ
Power Dissipation [B]	T_A=25℃	P_D	3.1	W
	T_A=70℃		2	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	℃

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	32	40	℃/W
Maximum Junction-to-Ambient [A D]	Steady-State		60	75	℃/W
Maximum Junction-to-Lead	Steady-State	$R_{\theta JL}$	17	24	℃/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=1mA, V_{GS}=0V	30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=30V, V_{GS}=0V			0.5	mA
		T_J=125°C			100	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}= ±12V			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250µA	1.1	1.65	2.1	V
$I_{D(ON)}$	On state drain current	V_{GS}=10V, V_{DS}=5V	68			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=13A		9	11	mΩ
		T_J=125°C		13	16	
		V_{GS}=4.5V, I_D=11A		10.7	14	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=13A		80		S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.4	0.7	V
I_S	Maximum Body-Diode Continuous Current				5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz	930	1170	1400	pF
C_{oss}	Output Capacitance		90	128	170	pF
C_{rss}	Reverse Transfer Capacitance		45	89	125	pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz	0.7	1.4	2.1	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=15V, I_D=13A	16	20	24	nC
Q_g(4.5V)	Total Gate Charge		7	8.7	10.5	nC
Q_{gs}	Gate Source Charge			3.2		nC
Q_{gd}	Gate Drain Charge			3		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=15V, R_L=1.2Ω, R_{GEN}=3Ω		6		ns
t_r	Turn-On Rise Time			2.4		ns
$t_{D(off)}$	Turn-Off DelayTime			23		ns
t_f	Turn-Off Fall Time			4		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=13A, dI/dt=500A/µs	5.5	7	8.5	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=13A, dI/dt=500A/µs	5	6.5	8	nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The value in any given application depends on the user's specific board design.
B. The power dissipation P_D is based on $T_{J(MAX)}$=150° C, using ≤ 10s junction-to-ambient thermal resistance.
C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150° C. Ratings are based on low frequency and duty cycles to keep initialT_J=25° C.
D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of $T_{J(MAX)}$=150° C. The SOA curve provides a single pulse rating.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

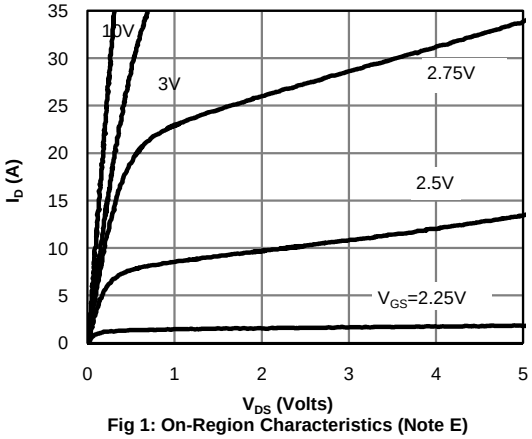


Fig 1: On-Region Characteristics (Note E)

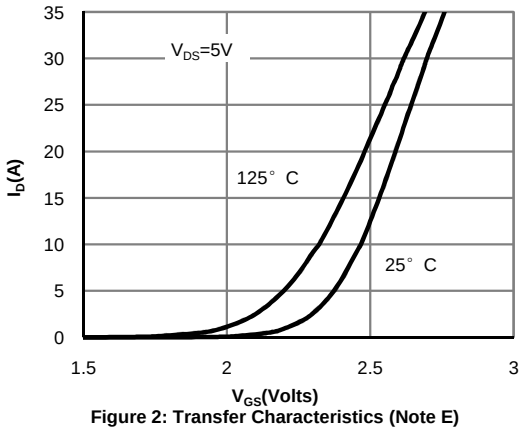


Figure 2: Transfer Characteristics (Note E)

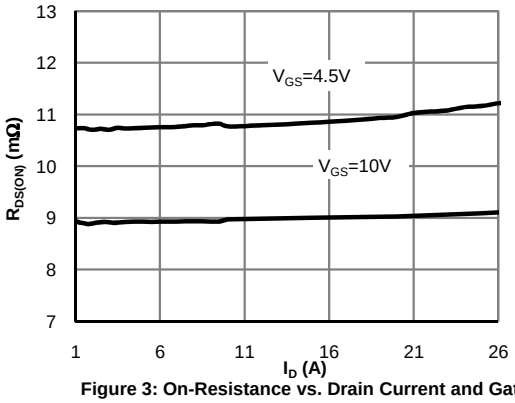


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

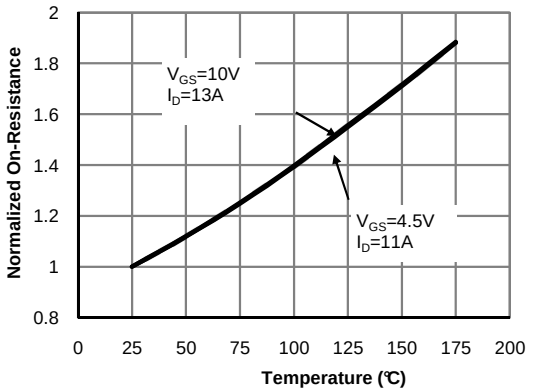


Figure 4: On-Resistance vs. Junction Temperature (Note E)

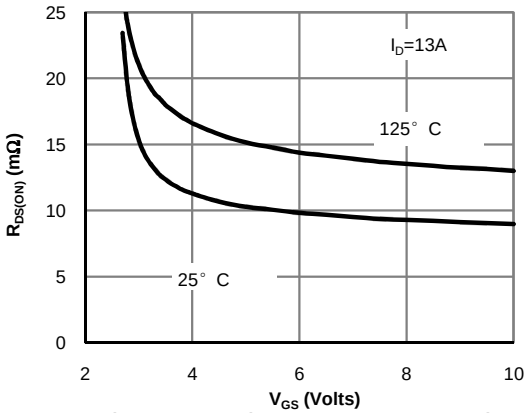


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

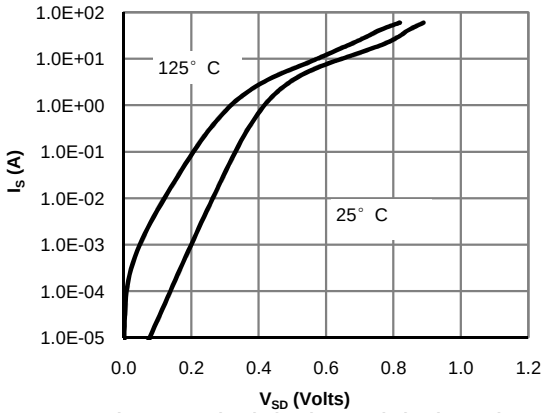


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

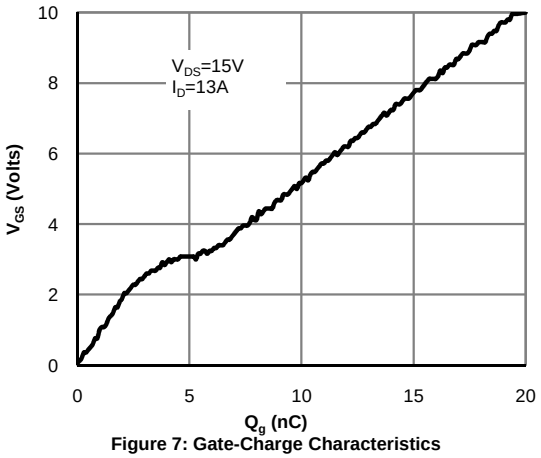


Figure 7: Gate-Charge Characteristics

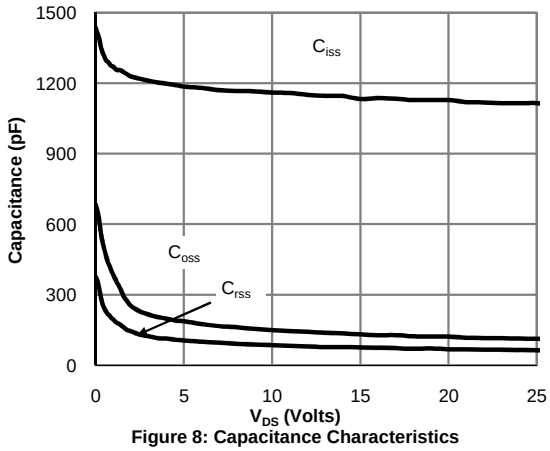


Figure 8: Capacitance Characteristics

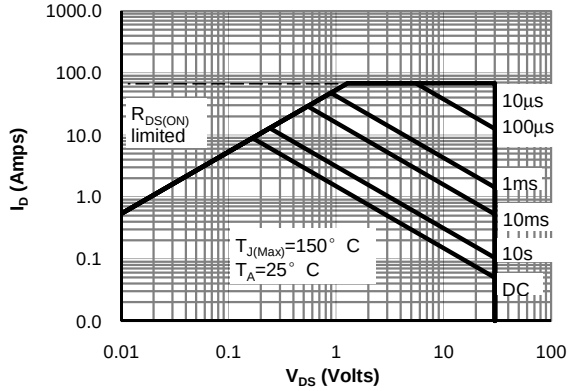


Figure 10: Maximum Forward Biased Safe Operating Area (Note F)

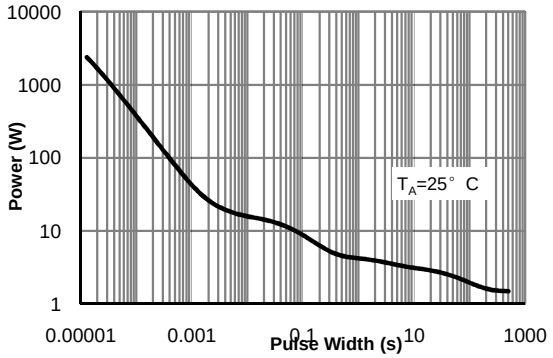


Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)

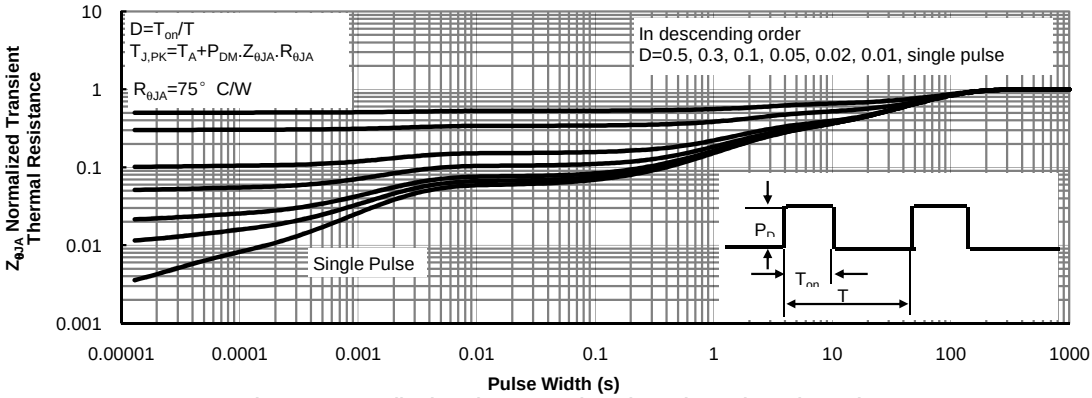


Figure 12: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

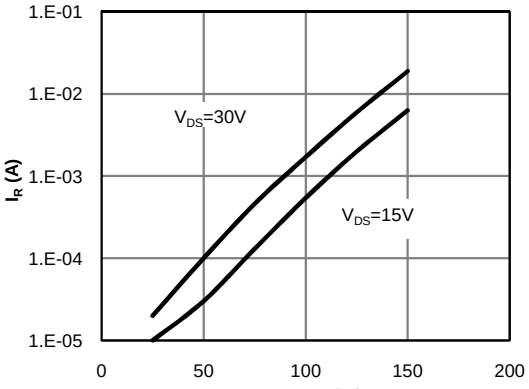


Figure 13: Diode Reverse Leakage Current vs. Junction Temperature

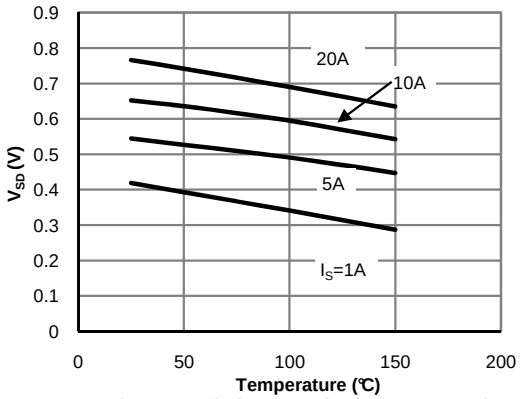


Figure 14: Diode Forward voltage vs. Junction Temperature

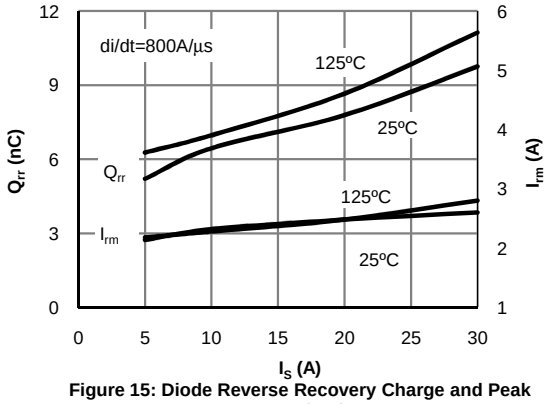


Figure 15: Diode Reverse Recovery Charge and Peak Current vs. Conduction Current

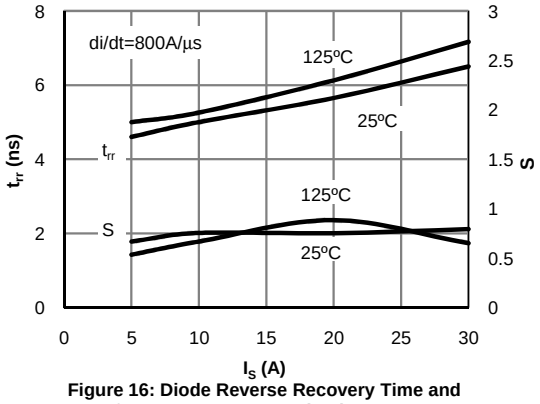


Figure 16: Diode Reverse Recovery Time and Softness Factor vs. Conduction Current

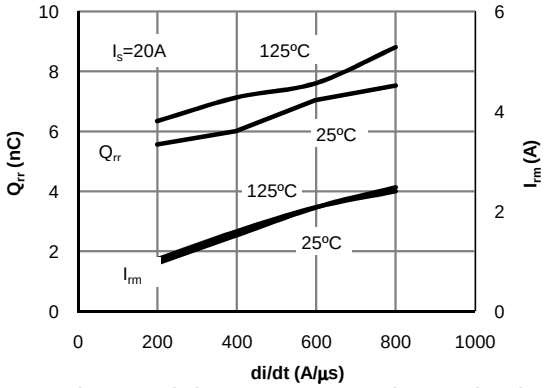


Figure 17: Diode Reverse Recovery Charge and Peak Current vs. di/dt

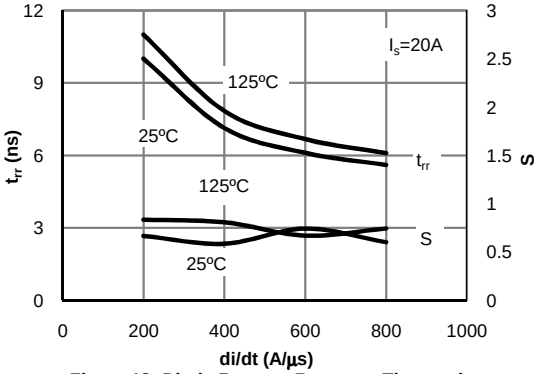
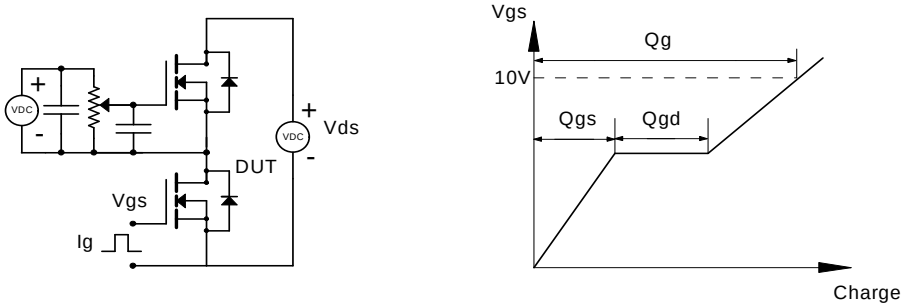
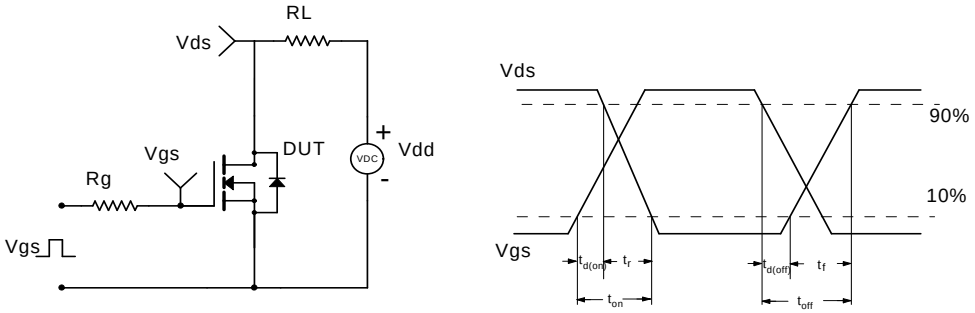


Figure 18: Diode Reverse Recovery Time and Softness Factor vs. di/dt

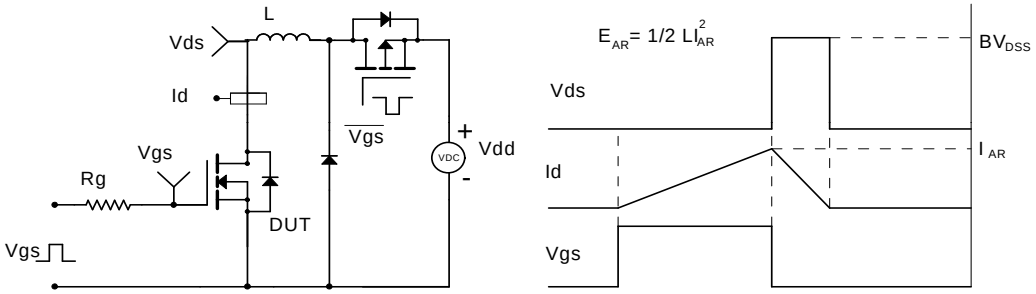
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms